

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|---------|---|--|------------------|---------|------------------|
| L1 | 4440680 | substrate carrier board pcb wcb ((printed wiring circuit circuitry multilayer multi) adj4 board) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/29 16:07 |
| L2 | 1355987 | board pcb wcb ((printed wiring circuit circuitry multilayer multi) adj4 board) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/29 16:07 |
| L3 | 1744202 | (upper lower top bottom first second) with (semiconductor dice chip die ic (integrated adj circuit) electronic component) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/29 16:10 |
| L4 | 89219 | 2 same 3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/29 16:12 |
| L5 | 61473 | 2 with 3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/29 16:13 |
| L6 | 10199 | (bga bump ball flipchip (flip adj chip)) same 4 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/29 16:13 |
| L7 | 6548 | 5 same 6 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/29 16:14 |
| L8 | 933 | 7 and (mother motherboard) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/29 16:14 |